

Title (en)

METHOD AND DEVICE FOR THE THERMAL TREATMENT OF SUBSTRATES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM THERMISCHEN BEHANDELN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF POUR EFFECTUER LE TRAITEMENT THERMIQUE DE SUBSTRATS

Publication

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Application

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- EP 0205683 W 20020523

Abstract (en)

[origin: WO02095804A1] The object of the invention is to measure temperature using pyrometers, in a simple and economic way, enabling precise temperature measurement, even for low temperatures. The invention presents a device and method for thermally treating substrates, wherein the substrate is exposed to at least a first and at least a second radiation; the predetermined wavelengths of the first radiation are absorbed between the first radiation source and the substrate; a radiation from the substrate is measured in the predetermined wavelength using a radiation detector arranged on the same side as a second radiation source; the second radiation from the second radiation source is modulated and determined.

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IPC 8 full level

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Citation (search report)

See references of WO 02095804A1

Citation (examination)

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DOCDB simple family (application)

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